Meeting Notes January 10,2013

Attendees: Stephen Kaye, Roger Smith, A. N. Ramaprakash, Pravin Chordia, Mahesh Burse

**Minutes**

**IUCAA**

* Packaging (enclosure layout, card format, etc) requirements submitted by Caltech have been accepted by IUCAA, though further discussion is required to resolve some details.
* Printed circuit boards were already ordered when change in packaging document was released
* IUCAA has the proceeded with the old packaging and board layout
* Backplane board, timing board, and analog board are all in house.
* Testing will take place in the coming weeks for the boards
* Tests for analog card will only involve two channels
* In 8-9 weeks, testing of cards will be complete to the point of connecting system to a 2k x 2k CCD.
* Will initiate new layout for the new packaging concept; design is to be mutually agreed before commencing this work.

**Caltech**

* Mechanical portion of project is proceeding quickly. Wants to make sure electronics also continues to mature.
* Has some questions about analog board which will be presented in document on twiki
* Requested documents describing designs to be tested, including schematics, layout, description containing (for example) description of design concept, goals and requirements, projected performance, configuration options, connector signals and layout, ground and power distribution, filtering and current return paths.
* Requested test documents describing
	+ What tests that have been performed or planned for analog and timing boards.
	+ Description of test methods.
	+ Quantitative results and tables comparing predicted and measured performance.

**Action Items**

**IUCAA**

* Post documents on twiki of test procedures and test results (if any)
* Post pictures of IFPAC system as it exists now

**Caltech**

* Post document containing questions/concerns about analog card.
* Post proposed schedule for IFPAC design reviews and deliveries.